

WHAT IS CLAIMED IS:

1. A printed wiring substrate comprising:

a core substrate having a front surface and a back surface; and

an electronic component embedded via a resin in a through-hole
extending through said core substrate between the front surface and back
5 surface of the core substrate;

said printed wiring substrate characterized in that:

said electronic component has an electrode projecting from at least
either an upper end or a lower end thereof; and

the resin contains an inorganic filler.

2. A printed wiring substrate comprising:

a core substrate having a front surface and a back surface; and

an electronic component embedded via a resin in a recess formed in
said core substrate and extending from an interior of said core substrate to the
5 front surface or back surface of the core substrate;

said printed wiring substrate characterized in that:

said electronic component has an electrode projecting from at least
either an upper end or a lower end thereof; and

the resin contains an inorganic filler.

3. A printed wiring substrate comprising:

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a core substrate having a front surface and a back surface; and

an electronic component embedded in said core substrate;

said printed wiring substrate characterized in that:

- 5 said electronic component has an electrode projecting from at least either an upper end or a lower end thereof; and

said core substrate contains an inorganic filler.

4. The printed wiring substrate as claimed in claim 1, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

5. The printed wiring substrate as claimed in claim 2, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

6. The printed wiring substrate as claimed in claim 3, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

7. The printed wiring substrate as claimed in claim 1, wherein the inorganic filler has a particle size not greater than 25 μm , and the electrode has a height of at least 50 μm .

8. The printed wiring substrate as claimed in claim 2, wherein the inorganic filler has a particle size not greater than 25 μm , and the electrode has a height of at least 50 μm .

9. The printed wiring substrate as claimed in claim 3, wherein the inorganic filler has a particle size not greater than 25 μm , and the electrode has a height of at least 50 μm .

10. The printed wiring substrate as claimed in claim 4, wherein the inorganic filler has a particle size not greater than 25 μm , and the electrode has a height of at least 50 μm .

11. A method for manufacturing a printed wiring substrate
5 comprising a core substrate having a front surface and a back surface and an electronic component embedded via a resin in a through-hole extending through the core substrate between the front surface and back surface of the core substrate or in a recess formed in the core substrate and extending from an interior of the core substrate to the front surface or the back surface, said
10 method comprising the steps of:

inserting into the through-hole or the recess the electronic component having an electrode projecting from at least either an upper end or a lower end thereof;

embedding the electronic component in the through-hole or the recess
15 by means of a resin containing an inorganic filler; and

polishing a surface of the resin so as to expose an end surface of the electrode.